

ABSTRACT

The present invention provides a resin applied-copper foil, which is free of halogen elements, having high flame retardancy, excellent water resistance, heat resistance, and good peeling strength between a base material and copper foil.

To provide the a resin compound used for fabricating an interlayer dielectric of a printed wiring board, the resin compound comprises an epoxy-based resin which includes: an epoxy resin curing agent having 5 to 25% by weight of nitrogen; and maleimide compounds having thermosetting properties, and the resin compound furthrt has composition which is free of halogen elements.